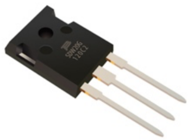
MATERIAL DECLARATION SHEET

BOURNS®

Material Number	BSDW20G120C2 TO247-3			
Product Line	Semiconductor			
Compliance Date	2023-3-22			
RoHS Compliant	YES，7(a)	MSL	N.A.	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	4.98	Silicon Carbide (SiC)	409-21-2	100	0.08	0.08
2	Die Attach	Silver	0.11	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.00	0.03
			2.04	Silver (Ag)	7440-22-4	95	0.03	
3	Lead Frame	Copper alloy	1.2	Phosphorous (P)	7723-14-0	0.03	0.02	67.10
			1.2	Nickel (Ni)	7440-02-0	0.03	0.02	
			4.01	Iron (Fe)	7439-89-6	0.1	0.07	
			4004.68	Copper (Cu)	7440-50-8	99.84	66.99	
4	Mold Compound	Resin	125.36	Phenol Formaldehyde resin (generic)	9003-35-4	6.5	2.1	32.27
			308.58	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	16	5.16	
			1369.31	Silica fused	60676-86-0	71	22.91	
			125.36	Metal hydroxide	Trade Secret	6.5	2.1	
5	Post-plating	Lead alloy	27.20	Tin (Sn)	7440-31-5	100	0.45	0.45
6	Wire	Pure metal	3.88	Aluminium (Al)	7429-90-5	100	0.06	0.06
		Total weight	5977.91 mg					

This Document was updated on: 2023/3/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which is exempt from the requirements

7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)